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|---|--|
| <p>1. Name of conveying party(ies) Seichi Nakamura, Hideki Nishihata, Riyuusuke Kasamatsu, Kazunori Tsubuku, Akira Bando, Nobuo Tsumaki, Tomoji Watanabe, Kazuo Mera, Tsuneo Hayashi, Yoichi Kurosawa</p> <p>Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p> | <p>2. Name and address of receiving party(ies) Name: <u>Sumco Corporation</u> Internal Address: _____ _____ Street Address: <u>2-1, Shibaura 1-chome</u> _____ Minato-ku _____ City: <u>Tokyo</u> _____ State: _____ _____ Country: <u>Japan</u> Zip: _____ _____</p> <p>Additional name(s) & address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p> |
| <p>3. Nature of conveyance/Execution Date(s): Execution Date(s) <u>January 10, 2007</u></p> <p><input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Joint Research Agreement <input type="checkbox"/> Government Interest Assignment <input type="checkbox"/> Executive Order 9424, Confirmatory License <input type="checkbox"/> Other _____</p> | <p>4. Application or patent number(s): <input type="checkbox"/> This document is being filed together with a new application.</p> <p>A. Patent Application No.(s) <u>11/510,277</u></p> <p>B. Patent No.(s) _____</p> <p>Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p> |
| <p>5. Name and address to whom correspondence concerning document should be mailed: Name: <u>Anton E. Skaugset</u> Internal Address: <u>Kolisch Hartwell, P.C.</u> _____ Street Address: <u>520 S.W. Yamhill Street, Suite 200</u> _____ City: <u>Portland</u> _____ State: <u>Oregon</u> Zip: <u>97204</u> _____ Phone Number: <u>(503) 224-6655</u> _____ Fax Number: <u>(503) 295-6679</u> _____ Email Address: <u>anton@khpatent.com</u></p> | <p>6. Total number of applications and patents involved: <u>one</u></p> <p>7. Total fee (37 CFR 1.21(h) & 3.41) \$ <u>40.00</u></p> <p><input type="checkbox"/> Authorized to be charged by credit card <input checked="" type="checkbox"/> Authorized to be charged to deposit account <input type="checkbox"/> Enclosed <input type="checkbox"/> None required (government interest not affecting title)</p> <p>8. Payment Information</p> <p>a. Credit Card Last 4 Numbers _____ Expiration Date _____</p> <p>b. Deposit Account Number <u>11-1540</u> Authorized User Name <u>Kolisch Hartwell, P.C.</u></p> |
| <p>9. Signature: <u>Anton E. Skaugset</u> _____ January 11, 2007 _____ Signature Date Anton E. Skaugset _____ Name of Person Signing</p> <p style="text-align: right;">Total number of pages including cover sheet, attachments, and documents: 8</p> | |

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
 Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450 KH File: SHX 377

copy to (10/1/07)

ASSIGNMENT

WHEREAS, WE, (1) Seichi NAKAMURA; (2) Hideki NISHIHATA; (3) Riyusuke KASAMATSU; (4) Kazunori TSUBUKU; (5) Akira BANDO; (6) Nobuo TSUMAKI; (7) Tomoji WATANABE; (8) Kazuo MERA; (9) Tsuneo HAYASHI; and (10) Yoichi KUROSAWA

Of (1) - (3) c/o SUMCO CORPORATION, 2-1, Shibaura 1-chome, Minato-ku, Tokyo, Japan; (4) c/o Hitachi Ltd, 1-1, Saiwai-cho 3-chome, Hitachi-shi, Ibaraki-ken, Japan; (5) c/o Hitachi Ltd, 2-1, Oomika-cho 5-chome, Hitachi-shi, Ibaraki-ken, Japan; (6) c/o Matsudo Research Laboratory, Hitachi Plant Technologies Ltd., 537, Kami-Hongo, Matsudo-shi, Chiba-Ken, Japan; (7) c/o Mechanical Engineering Research Laboratory, Hitachi Ltd., 832-2 Horiguchi, Hitachinaka-shi, Ibaraki-ken, Japan; (8) and (10) c/o Hitachi High-Technologies Corporation, 882, Ichige, Hitachinaka-shi, Ibaraki-ken, Japan; and (9) c/o Hitachi Ltd, 2520, Takaba, Hitachinaka-shi, Ibaraki-ken, Japan

respectively, have invented certain improvements in

APPARATUS FOR MANUFACTURING SEMICONDUCTOR SUBSTRATES

, for which we have executed an application for Letters Patent of the United States on the date we executed this Assignment as hereinafter set forth.

WHEREAS, SUMCO CORPORATION, a Japanese corporation, having its principal place of business in Tokyo, Japan, is desirous of acquiring an interest therein:

NOW, THEREFORE, for other good and valuable consideration, we the said

(1) Seiichi NAKAMURA; (2) Hideki NISHIHATA; (3) Rynnusuke KASAMATSU; (4) Kazunori TSUBUKU; (5) Akira BANDO; (6) Nobuo TSUMAKI; (7) Tomoji WATANABE; (8) Kazuo MERA; (9) Tsuneo HAYASHI; and (10) Yoichi KUROSAWA

, have sold, assigned, and transferred, and by these presents do sell, assign, and transfer unto the said **SUMCO CORPORATION**, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions in any and all foreign countries and in and to any and all divisions, reissues, continuations and extensions thereof.

We hereby authorize and request the Patent Office officials in the United States and any and all foreign countries to issue any and all of said Letters Patent, when granted, to the said **SUMCO CORPORATION**, as the assignee of our entire right, title and interest in and to the same, for the sole use of the said **SUMCO CORPORATION**, its successors and assigns.

Further, we agree that we will communicate to the said **SUMCO CORPORATION**, or its representatives any facts known to us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitution, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to the said **SUMCO CORPORATION**, make all rightful oaths and generally do everything possible to aid the said **SUMCO CORPORATION**, its successors and assigns, to obtain and enforce proper protection for said invention in the United States and in any and all foreign countries.

(7/9)

IN TESTIMONY WHEREOF, I have hereunto set my hand this 10th day of January, 2007.

(4/7)

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